

Title (en)

FLOOR PANEL AND FLOOR PANEL ASSEMBLY PROCESS

Title (de)

BODENPLATTE UND BODENPLATTENANORDNUNGSVERFAHREN

Title (fr)

PANNEAU DE PLANCHER ET PROCÉDÉ D'ASSEMBLAGE DE PANNEAU DE PLANCHER

Publication

EP 4332322 A2 20240306 (EN)

Application

EP 23193654 A 20230828

Priority

SI 202200145 A 20220829

Abstract (en)

The invention relates to a floor panel (1) used in a flooring installation system. The floor panel (1) is configured in the form of a rectangular board having at least two joints provided on opposite sides in the form of a receiving element (2) on one side and a connecting element (3) on the opposite side, wherein, when the floor panels (1) are being assembled, the connecting element (3) fits into the receiving element (2) in a form-locking manner, thus ensuring a tight joint between two adjacent panels (1). The floor panel (1) is provided on its bottom face with equidistantly spaced floor grooves (4) in longitudinal and transverse directions. On the sides intended for a receiving element (2), the floor panel (1) is provided with vertical grooves (5) extending from the bottom surface of the floor panel (1) through the receiving element (2). The vertical grooves (5) are preferably equidistantly spaced, wherein each vertical groove (5) continuously continues into the corresponding floor groove (4). The vertical groove (5) is formed in its upper portion in the form of a slot (5a), while it is formed in its bottom portion in the form of an extension (5b) that continuously continues into the floor groove (4).

IPC 8 full level

E04F 15/02 (2006.01)

CPC (source: EP)

E04F 15/02005 (2013.01); **E04F 15/02038** (2013.01); **E04F 2201/0153** (2013.01); **E04F 2203/08** (2013.01)

Citation (applicant)

- EP 1261785 A1 20021204 - E F P FLOOR PROD FUSSBOEDEN [AT]
- EP 1585867 A1 20051019 - REDDING JOHN [GB]
- EP 2718516 A1 20140416 - FRITZ EGGER GMBH & CO OG [AT]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC ME MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

EP 4332322 A2 20240306; **EP 4332322 A3 20240313**; SI 26412 A 20240329

DOCDB simple family (application)

EP 23193654 A 20230828; SI 202200145 A 20220829